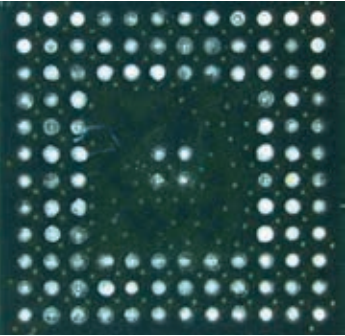




# REBALL & SOLDERABILITY TEST SERVICE

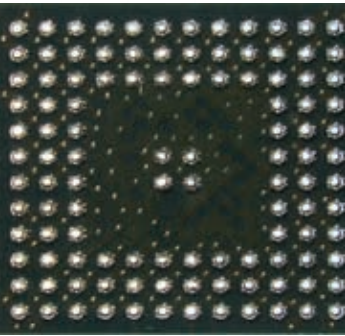
- REBALL SERVICES WITH FAST TURN AROUND TIMES
- X-RAY ANALYSIS FOR REBALL QUALITY CHECK
- PRECONDITIONING PRIOR TO SOLDERABILITY
- WETTING BALANCE SOLDERABILITY
- DIP AND LOOK SOLDERABILITY

# REBALL AND SOLDERABILITY TEST



## REBALL SERVICE

- FinePlacer 145 PICO Rework station
- Sample dimensions from 1.25 mm x 1.25 mm up to 90 mm x 70 mm
- Board sizes up to 400 mm x 234 mm
- Placement accuracy < 5 µm
- Inhouse design/manufacturing of dedicated sample holder and grid
- Ball diameter range of 0.090 mm up to 0.300 mm



## SMD REFLOW

- Heller 1707 Mk III 7-zone
- Full Forced Air Convection
- Maximum temperature of 350 °C
- MSL Preconditioning according to EIA/IPC/JEDEC J-STD-002
- SMD reflow solderability test of QFN/LGA packages according to JESD22-B102/ JEDEC J-STD-002D



## DIP AND LOOK / WETTING BALANCE

- Metronelec ST60
- Solder bath, SnPb and Pb free alloys
- Temperature range of +50 °C up to +400 °C
- Solder globule test: 2mm and 4mm
- Dip and Look according to test standards:
  - JESD22-B102 / JEDEC J-STD-020D / MIL-STD-883
- Wetting balance test standards:
  - IEC60668-2-69 / NF89400



## PRECONDITIONING PRIOR TO SOLDERABILITY TEST

- Dry heat: 4 hrs @ 155°C
- Steam aging: 8hrs